



06-18-2001



Docket No.: 500.39919X00

EET

U.S. DEPARTMENT OF COMMERCE
Patent and Trademark Office

101752349

To the Honorable Commissioner of Patents and Trademarks, U.S. Department of Commerce, Patent and Trademark Office, Washington, D.C. 20503
and original documents or copy thereof.

1. Name of conveying party(ies):

Y. YAMAGUCHI, H. TENMEI, K. INOUE,
N. OROKU, H. HOZOJI, S. TSUNODA, N. KANDA
M. MOMAGAWA, I. ANJO, A. NISHIMURA, K. UJIE, A.
YAJIMA,Additional name(s) of conveying party(ies) attached? ☐ Yes ☒ No

3. Nature of conveyance:

- ☒ Assignment ☐ Merger
☐ Security Agreement ☐ Change of Name
☐ Other _____

Execution Date: May 15, 17, 18, 21, 25, 28, & June 1, 2001

2. Name and address of receiving party(ies):

Name: Hitachi, Ltd.

Street Address: 6, Kanda Surugadai 4-chome, Chiyoda-ku

City: Tokyo:

Country: Japan

Additional name(s) & address(es) attached? ☐ Yes ☒ No

4. Application number(s) or patent number(s):

If this document is being filed together with a new application, the execution date of the application is:

A. Patent Application No.(s)
09/811,401 Filed March 20, 2001

B. Patent No.(s)

Additional numbers attached? ☐ Yes ☒ No

5. Name and address of party to whom correspondence concerning document should be mailed:

Name: ANTONELLI, TERRY, STOUT & KRAUS, LLP

Internal Address:

Street Address: 1300 North Seventeenth Street
Suite 1800

City: Arlington State: VA Zip: 22209

6. Total number of applications and patents involved: 1

7. Total fee (37 CFR 3.41).....\$40.00

- ☒ Enclosed
☒ Any deficiencies may be charged to deposit account
☐ Authorized to be charged to deposit account

8. Deposit account number: 01-2135

(Attach duplicate copy of this page if paying by deposit account)

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9. Statement and signature.

To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy of the original document.

Gregory E. Montone

Name of Person Signing

Signature

June 13, 2001

Date

Attorney Registration No. 28,141

Total number of pages including cover sheet, attachments, and document: 2

OMB No. 0651-0011 (exp. 4/94)

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ASSIGNMENT (譲渡証)

As a below named inventor, I hereby declare that:

IN CONSIDERATION of the sum of One Dollar (\$1.00) or the equivalent thereof, and other good and valuable consideration paid to me citizen of Japan by HITACHI, LTD., a corporation organized under the laws of Japan, located at 6, Kanda Surugadai 4-chome, Chiyoda-ku, Tokyo, Japan, receipt of which is hereby acknowledged I do hereby sell and assign to said HITACHI, LTD., its successors and assigns, all my right, title and interest, in and for the United States of America, in and to

SEMICONDUCTOR DEVICE AND METHOD FOR MANUFACTURING THE SAME AND SEMICONDUCTOR DEVICE-MOUNTED STRUCTURE

*U.S. Serial No. 09/811401 filed on March 20, 2001
invented by me (if only one is named below) or us (if plural inventors are named below) and described in the application for United States Letters Patent therefor, executed on even date herewith, and all United States Letters Patent which may be granted therefor, and all divisions, continuations and extensions thereof, the said interest being the entire ownership of the said Letters Patent when granted, to be held and enjoyed by said HITACHI, LTD., its successors, assigns or other legal representatives, to the full end of term for which said Letters Patent may be granted, as fully and entirely as the same would have been held and enjoyed by me or us if this assignment and sale had not been made;

And I hereby agree to sign and execute any further documents or instruments which may be necessary, lawful, and proper in the prosecution of the above-named application or in the preparation and prosecution of any continuing, continuation-in-part, substitute, divisional, renewal, reviewed or reissue applications or in any amendment, extension, or interference proceedings, or otherwise to secure the title thereto in said assignee;

And I do hereby authorize and request the Commissioner of Patents to issue said Letters Patent to said HITACHI, LTD.

Signed on the date(s) indicated aside signatures:

INVENTOR(S)

(発明者フルネームサイン)

Date Signed

(署名日)

1) <u>Toshifide Tamaguchi</u>	<u>1 / June / 2001</u>
2) <u>Hiroguki Tenmei</u>	<u>17 / May / 2001</u>
3) <u>Kosuke Inoue</u>	<u>May 21, 2001</u>
4) <u>Naoyuki Orokau</u>	<u>21 - May. 2001</u>
5) <u>Binshi Horiji</u>	<u>15 / May / 2001</u>
6) <u>Shigetame Tsunoda</u>	<u>17 / May / 2001</u>
7) <u>Naoya Kanda</u>	<u>17 / May / 2001</u>
8) <u>Madoka Minagawa</u>	<u>28 / May / 2001</u>
9) <u>Ichiro Anzaki</u>	<u>25 / May / 2001</u>
10) <u>Asao Nishimura</u>	<u>5 / 18 / 2001</u>

PATENT

REEL: 011890 FRAME: 0743

E 5872-91
A

ASSIGNMENT
(譲 渡 証)

As a below named inventor, I hereby declare that:

IN CONSIDERATION of the sum of One Dollar (\$1.00) or the equivalent thereof, and other good and valuable consideration paid to me citizen of Japan by HITACHI, LTD., a corporation organized under the laws of Japan, located at 6, Kanda Surugadai 4-chome, Chiyoda-ku, Tokyo, Japan, receipt of which is hereby acknowledged I do hereby sell and assign to said HITACHI, LTD., its successors and assigns, all my right, title and interest, in and for the United States of America, in and to

SEMICONDUCTOR DEVICE AND METHOD FOR MANUFACTURING THE SAME AND
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And I hereby agree to sign and execute any further documents or instruments which may be necessary, lawful, and proper in the prosecution of the above-named application or in the preparation and prosecution of any continuing, continuation-in-part, substitute, divisional, renewal, reviewed or reissue applications or in any amendment, extension, or interference proceedings, or otherwise to secure the title thereto in said assignee;

And I do hereby authorize and request the Commissioner of Patents to issue said Letters Patent to said HITACHI, LTD.

Signed on the date(s) indicated aside signatures:

INVENTOR(S)

(発明者フルネームサイン)

Date Signed

(署名日)

11)	<u>Kenji Ujii</u>	<u>18/may/2001</u>
12)	<u>Akira Yajima</u>	<u>15/may/2001</u>
13)	_____	_____
14)	_____	_____
15)	_____	_____
16)	_____	_____
17)	_____	_____
18)	_____	_____